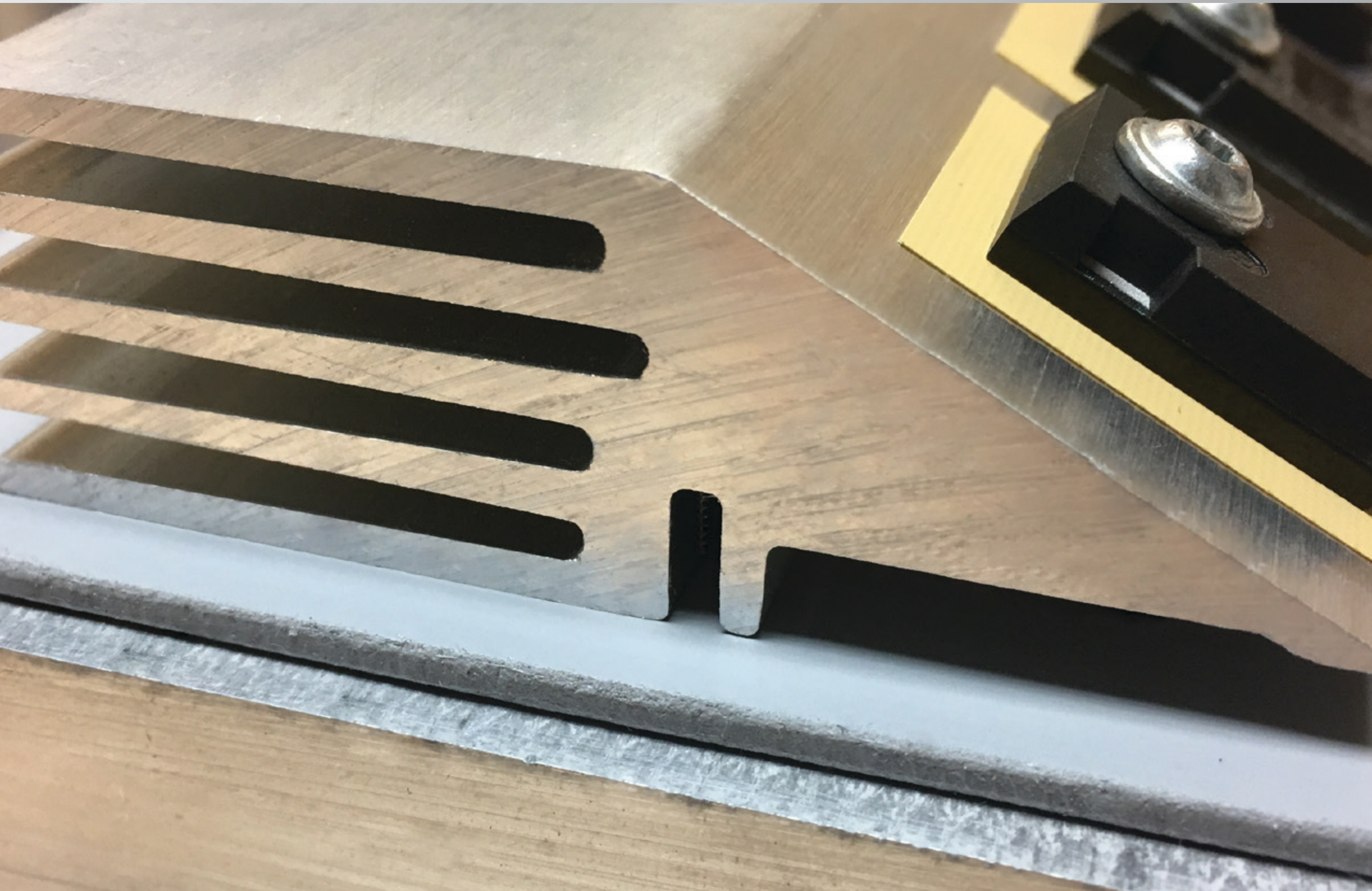
BERGQUIST®



BERGQUIST® GAP PAD® TGP 6000ULM

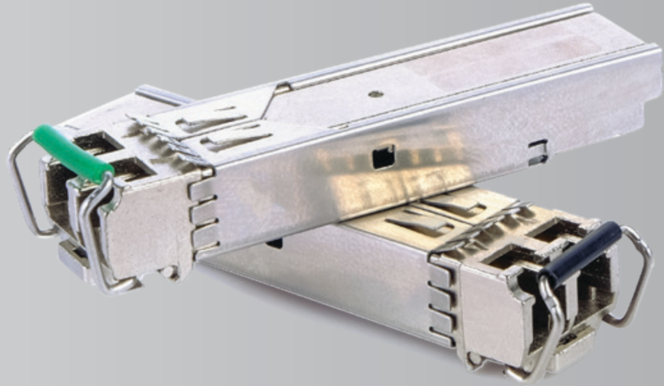
SILICONE GAP FILLING MATERIAL

For over 50 years, the BERGQUIST® brand has been the trusted leader in thermal management with technology platforms that deliver proven reliability for challenging applications. In keeping with its ongoing innovation initiatives, Henkel has brought to market the latest in the BERGQUIST® GAP PAD® family. For applications where high heat dissipation and low stress are required, Henkel has developed BERGQUIST® GAP PAD® TGP 6000ULM. Ideal for specific devices and systems in the power, computing, consumer, telecom and automotive sectors, BERGQUIST® GAP PAD® TGP 6000ULM offers high thermal conductivity of 6.0 W/m•K and an ultra-low modulus for reduced stress, particularly for small footprint components with high power density. The silicone-based, non-electrically conductive GAP PAD® is highly conformable, providing excellent coverage on various topographies. BERGQUIST® GAP PAD® TGP 6000ULM is easy to apply and reworkable, as the material provides a low- and a high-tack side and is available in custom-cut shapes for specific device and application requirements.

Henkel

Key Benefits

- Outstanding thermal performance
- Very low stress
- Ease of handling
- High-tack and low-tack sides
- Reworkable
- Excellent wet-out characteristics
- High dielectric strength



PROPERTIES		BERGQUIST® GAP PAD® TGP 6000ULM
Physical Properties	Young's Modulus (kPa)	41.3
Thermal Properties	Thermal Conductivity (W/m•K)	6
	Thermal Impedance, 30% Deflection (°C•in²/W)	0.26
Electrical Properties	Dielectric Strength (VAC)	> 5,000
	Volume Resistivity (Ω•m)	1×10^{10}
Safety Testing	Flammability Rating	UL 94 V-0

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